CLAIMS

1. An optical semiconductor element mounting package having a recessed part that serves as an optical semiconductor element mounting region, wherein the package is formed by integrating:

a resin molding composed of a thermosetting light-reflecting resin composition, which forms at least the side faces of the recessed part; and

at least a pair of positive and negative lead electrodes disposed opposite each other so as to form part of the bottom face of the recessed part, and

there is no gap at a joint face between the resin molding and the lead electrodes, and

the thermosetting light-reflecting resin composition contains (E) inorganic hollow particles.

2. The optical semiconductor element mounting package according to Claim 1, wherein the integration of the resin molding and the positive and negative lead electrodes is performed by transfer molding.

3. The optical semiconductor element mounting package according to Claim 1 or 2, wherein the thermosetting light-reflecting resin composition includes a filler.

4. The optical semiconductor element mounting package according to Claim 1 or 2, wherein the thermosetting light-reflecting resin composition further includes components: (A) an epoxy resin; (B) a curing agent; (C) a curing accelerator; (D) an inorganic filler; ~~(E) a white pigment;~~ and (F) a coupling agent, and is a resin composition whose optical reflectivity at a wavelength of 350 to 800 nm is at least 80% and which can be press molded at normal temperature (0 to 35°C).

5. The optical semiconductor element mounting package according to Claim 4, wherein the inorganic filler (D) is at least one type selected from the group consisting of silica, alumina, magnesium oxide, antimony oxide, aluminum hydroxide, magnesium hydroxide, barium sulfate, magnesium carbonate, and barium carbonate.

~~6. The optical semiconductor element mounting package according to Claim 4 or 5, wherein the white pigment (E) is inorganic hollow particles.~~

~~7~~6. The optical semiconductor element mounting package according to any of Claims ~~4 to 6~~1 to 5, wherein the average

particle size of ~~the white pigment~~ the inorganic hollow particles (E) is between 0.1 and 50 μm.

~~8~~7. The optical semiconductor element mounting package according to any of Claims ~~4 to 7~~4 to 5, wherein the total amount of the inorganic filler (D) and ~~the white pigment~~ the inorganic hollow particles (E) is from 70 to 85 vol% with respect to the entire thermosetting light-reflecting resin composition.

~~9. The optical semiconductor element mounting package according to any of Claims 1 to 8, wherein the spiral flow of the thermosetting light-reflecting resin composition is at least 50 cm and no more than 300 cm.~~

~~10. The optical semiconductor element mounting package according to any of Claims 1 to 9, wherein the disk flow of the thermosetting light-reflecting resin composition is at least 50 mm.~~

~~11~~8. The optical semiconductor element mounting package according to any of Claims 1 to ~~10~~7, wherein the coefficient of linear expansion of the thermosetting light-reflecting resin composition is 10 to 30 ppm/°C.

~~12~~9. An optical semiconductor device, comprising: the optical semiconductor element mounting package according to any of Claims 1 to ~~11~~8; an optical semiconductor element mounted on the bottom face of a recessed part of the package; and a transparent sealing resin layer that covers the optical semiconductor element in the recessed part.